

EPC-CV1

A1.01

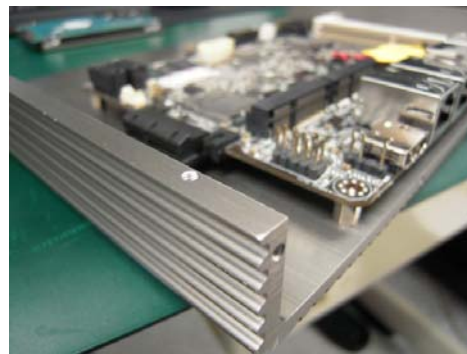
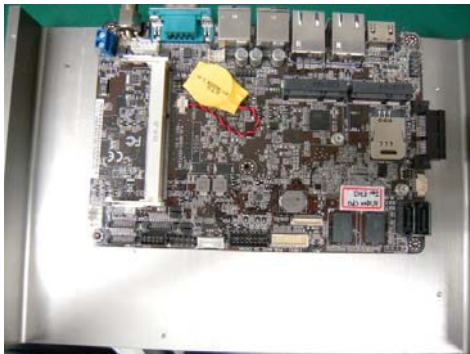
Thermal Image Analysis Report

Summary	<input type="checkbox"/> Pass <input type="checkbox"/> Fail <input checked="" type="checkbox"/> Pass with Deviation Comment: <u>Temperature at one component was estimated to be in marginal temperature point in comparison with component datasheet.</u>			
	Test Result Summary			
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	1
Defect Unsolved	0	0	0	1

Issue date	Approval	Test Engineer
2012 / 12 / 10	Tom Lin	Matthew Chi

Sample Configuration & Quantity Under Test

- **Model name** : EPC-CV1
- **CPU** : Intel Atom N2800 / 1.86GHz
- **Chipset** : Intel Cedarview
- **Memory** : Transcend 4G DDR3 SODIMM CL7
- **SATA HDD** : TOSHIBA MK1676GSX 2.5" 160G
- **BIOS** : 0201 X64(11/15/2012)
- **Test Software** : Windows 7 / Run PassMark Burn In Test 7.0
- **Power** : AT Power CWT DSA400P-C
- **Heat Sink:**



Thermal Image Analysis

1. Test Date: 2012-12-10

2. Test Product: EPC-CV1

3. Test Site: AAEON QE Dept.

4. Temperature Measurement:

4.1. 40 Channel Thermal Recorder:

4.1.1 YOKOGAWA Inc,

4.2.2 Model: DA100-13-1D

Date of Calibration: 2011/10/12

Serial Number: 12A323190

4.2. IR Scanner: Infrared Camera

4.2.1 NIPPON AVIONICS CO., LTD.

4.2.2 Model: NEC-G100D

Date of Calibration: 2012/01/03

Serial Number: 1051444

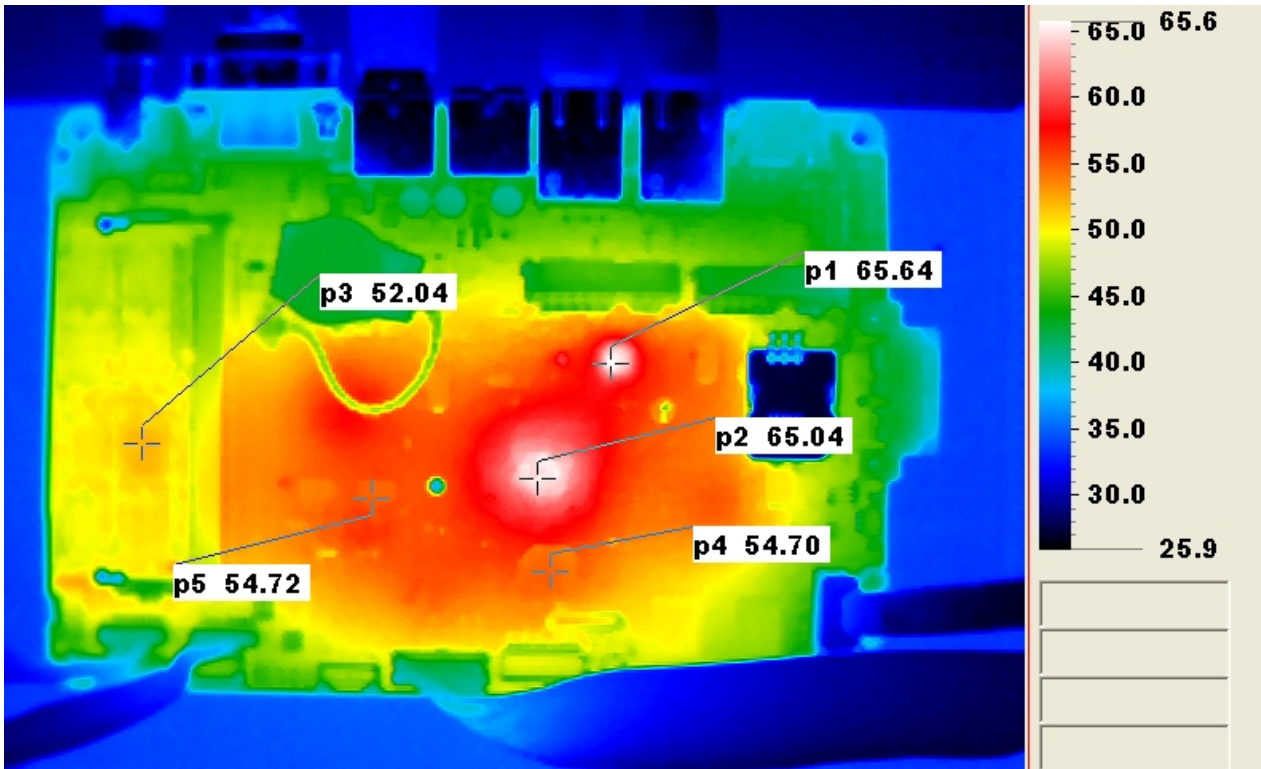
5. Test Condition:

Component Side-1 (Test by DA-100): 25.0°C With CPU Fan

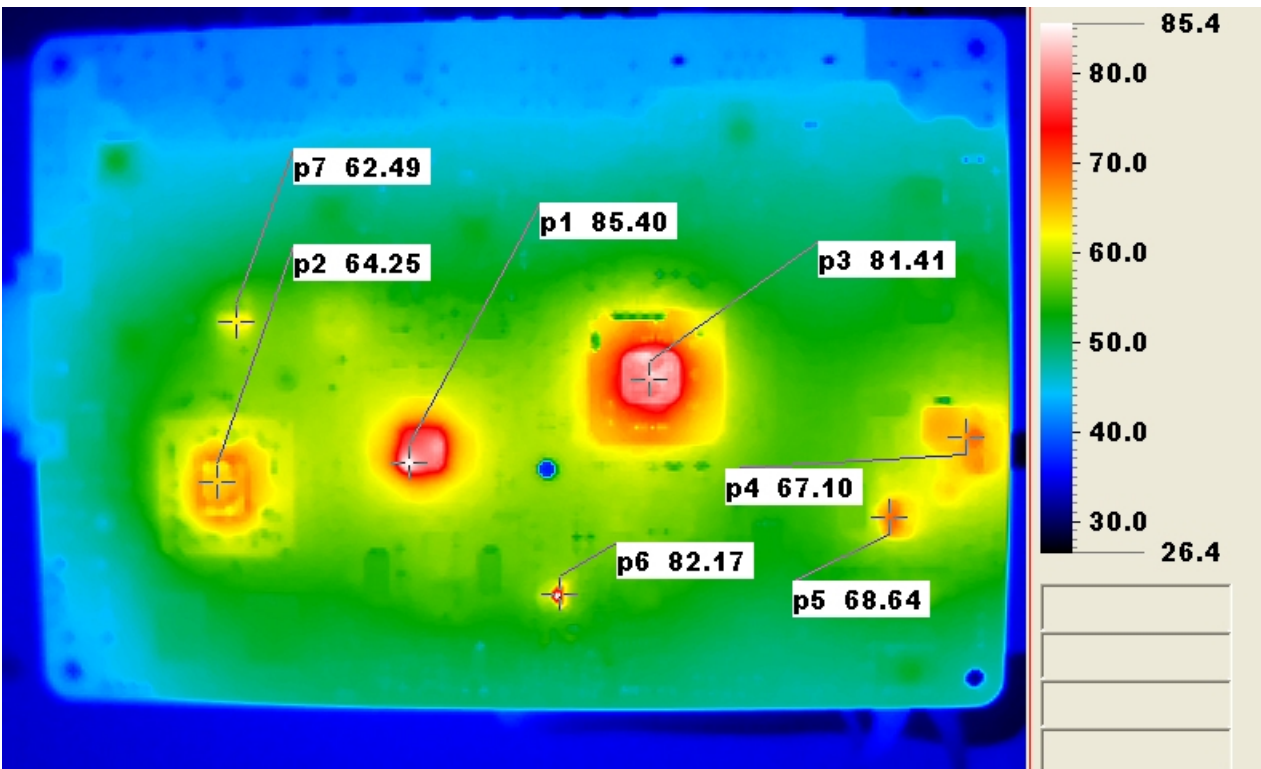
6. Take Picture Time:

After power on 2 hours

Temperature Profile Test:
Component Side:

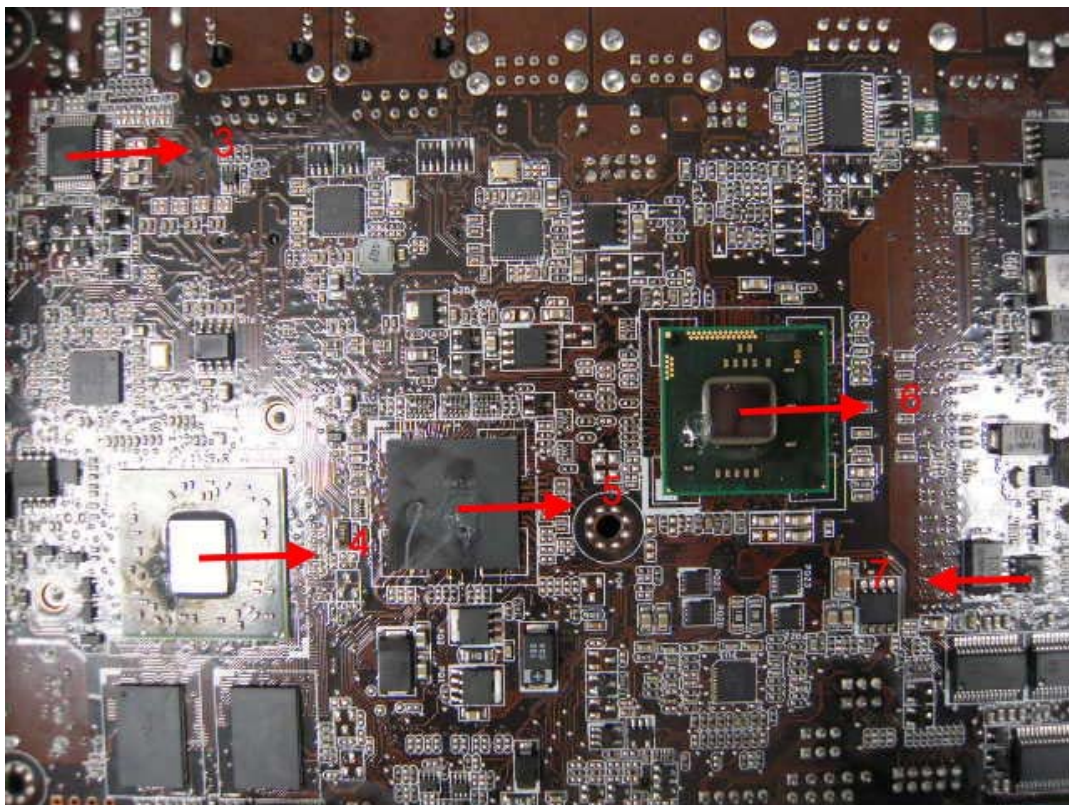
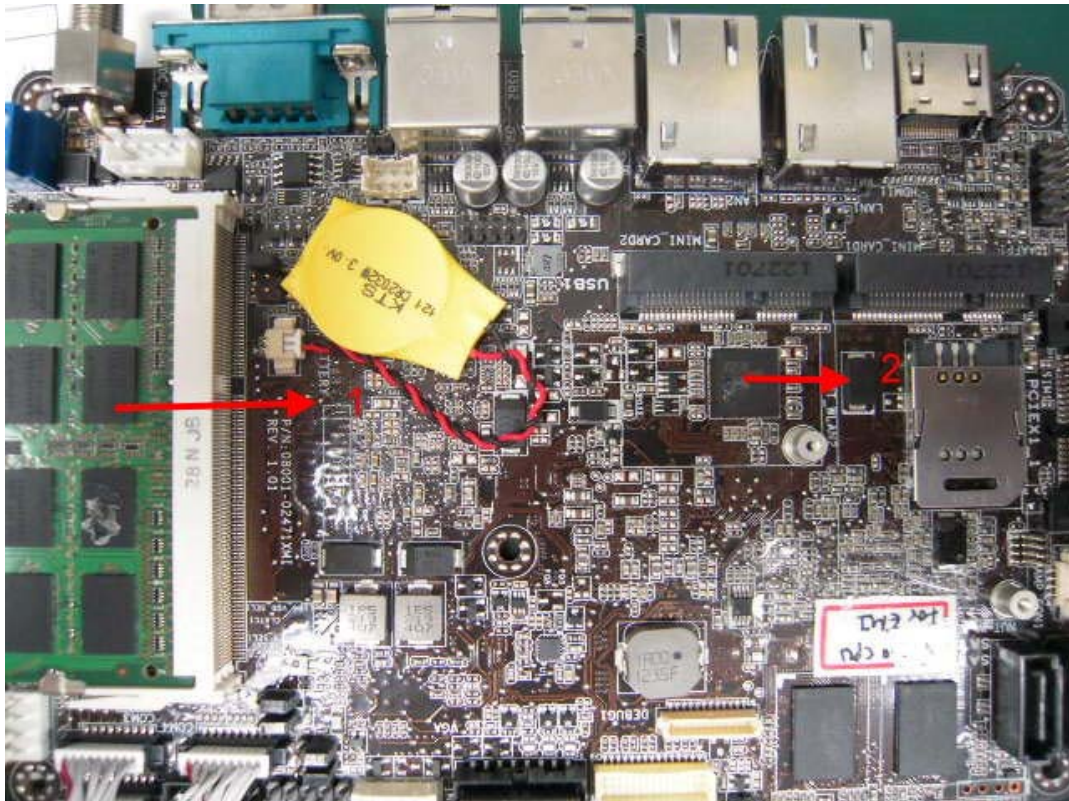


Solder Side:



Terminal Recorder:

Measuring Thermal Couple Position :



Using YOKOGAWA / DARWIN DA100-100-13-1D test

Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				25°C	55°C	
1	Memory	Transcend 4GB DDR3 SODIMM CL7	95	51.8	81.8	
2	U7	C.S PEX8605-AA50NI G QFN136//PLX	100	63.9	93.9	
3	U10	C.S ALC887-VD2-CG LQFP-48//REALTEK	100.5	49.7	79.7	
4	U27	C.S SEYMOUR-LP S3 FCBGA631//AMD 216-0809020 (A11)	105	46.6	76.3	
5	SU1	C.S CG82NM10 903500 INT TIGERPOINT NM10 SLGXX [HF].SMD	115	69.3	99.3	
6	U1	Intel Atom N2800 1.86GHz	100	51.7	81.7	
7	PU6	LDO REG. APE8955MP ESOP-8//APEC	125	40.1	70.1	

Note(*):

1. "Tc" indicates the component's case maximum temperature value specified in its datasheet.
2. "Tm" indicates the measured Tc value under working environmental temperature within product specification.

3. Judgment Criteria:

- **Fail** : $T_m > T_c + 5^{\circ}\text{C}$; The measured value is over specification plus margin.
- **Margin** : $T_c + 5^{\circ}\text{C} > T_m > T_c - 10^{\circ}\text{C}$; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
- **Pass** : $T_m < T_c - 10^{\circ}\text{C}$; The measured value is with safety margin.